IPC ASSOCIATION CONNECTINE ELECTRONICS INDUSTRIE	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				der both le	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Form Type Distribute				Form Type * Distribute		Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ials and Mfg Information			
upplier Inforn	nation														
Company name*			Company unique ID			Ţ	Unique ID Authority					Response Date*			
nsemi												2023-06-08			
Contact Name		Title - Contact			I	Phone - Contact*					Email - Contact*				
Product-Env-Stewa	ards	Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com					
uthorized Represe	entative*	Title - Representative			I	Phone - Representative*				Email - Representative*					
Product-Env-Stewards			Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com				
Requeste	er Item Number Mfr Item		Number			Effective Dat	te Vers	sion	Manufacturing Site		\	Weight*	UOM	Unit Type	
		pre-dri			PH PRE SENSOR OPEN; Single phase ore-driver with hall sensor method (open oop speed control)		2023-06-08			1	0.00	mg	Each		
Ianufacturing	Process Information	n													
Terminal Plating / Grid Array Material T			Cerminal Base Alloy J-STD-020 M		STD-020 MSL R	Rating	Peak Process Body Temperature Max		ime at Peak	ak Temperature Number of Reflow Cycles		cles			
contains Bi			CU Alloy 3				260 C 3		30		seconds 3				
comments															
TTENTION: MSI	L 3 Rated item requires Ba	ake and D	ry Pack (after	r electrical test)											
or more informati	on regarding material con	nposition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	2.68	mg	Supplier	Silicon (Si)	7440-21-3		2.6602	mg
			Supplier	Polyimide	Proprietary Data		0.0198	mg
Die Attach	0.55	mg	Supplier	Silver (Ag)	7440-22-4		0.3905	mg
			Supplier	Epoxy resins	129915-35-1		0.1595	mg
Lead Frame	5.07	mg	Supplier	Zinc (Zn)	7440-66-6		0.0066	mg
			Supplier	Iron (Fe)	7439-89-6		0.1191	mg
			Supplier	Copper (Cu)	7440-50-8		4.9402	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0041	mg
Mold Compound-Black	90.15	mg		Phenolic Resin	proprietary data		4.5075	mg
			Supplier	Epoxy Phenol Resin	Proprietary Data		2.5242	mg
			Supplier	Carbon Black (C)	1333-86-4		0.9015	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		2.7045	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		72.12	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		7.212	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		0.1803	mg
Plating	1.42	mg	В	Bismuth (Bi)	7440-69-9		0.0085	mg
			Supplier	Tin (Sn)	7440-31-5		1.4115	mg
Wire Bond - Cu	0.13	mg	Supplier	Copper (Cu)	7440-50-8		0.13	mg